

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims**

1. (original) A fabrication method for forming pores within a central area of a semi-conductive  
or conductive surface, comprising the steps of:  
forming a semi-conductive or conductive surface on a substrate in a manner  
ensuring that upon application of an electric field at the semi-conductive or conductive  
surface an intensity of the electric field at a central area of the surface is at least as great  
as an intensity of the electric field at a perimeter of the surface; and  
anodizing the semi-conductive or conductive surface by generating the electric  
field at the semi-conductive or conductive surface to form a porous region within the  
semi-conductive or conductive surface.
2. (original) A method according to claim 1 wherein the forming step further  
comprises:  
forming a dielectric layer on the substrate;  
removing a portion of the dielectric layer, leaving a remaining part of the  
dielectric layer and exposing a central region of the substrate; and  
forming the semi-conductive or conductive surface on a portion of the remaining  
part of the dielectric layer and on the central region of the substrate.
3. (original) A method according to claim 2 further comprising the step of anodizing  
the semi-  
conductive or conductive surface to form an anodized region in the semi-conductive or  
conductive surface above an area of contact between the semi-conductive or conductive surface  
and the substrate.
4. (original) A method according to claim 3, further comprising:  
forming a conductive layer on the semi-conductive or conductive surface;

forming a second conductive layer on the first conductive layer;  
forming a second dielectric layer on the second conductive layer;  
forming a third conductive layer on the second dielectric layer; and  
removing a portion of the second conductive layer, the second dielectric layer and  
the third conductive layer above the anodized region.

5. (original) A method according to claim 2, further comprising:  
forming a conductive layer on the semi-conductive or conductive surface;  
forming a second dielectric layer on the conductive layer;  
forming a second conductive layer on the second dielectric layer; and  
removing a portion of the first conductive layer, the second dielectric layer and the  
second conductive layer above an area of contact between the semi-conductive or  
conductive surface and the substrate, leaving a remaining part of the second conductive  
layer and exposing a central region of the semi-conductive or conductive surface.

6. (original) A method according to claim 5, further comprising:  
anodizing the central region of the semi-conductive or conductive surface to form  
an anodized region in the semi-conductive or conductive surface; and  
forming a third conductive layer on the remaining part of the second  
conductive layer and on the anodized region.

7. (original) A method according to claim 1 wherein the forming step further  
comprises:  
forming the semi-conductive or conductive surface on the substrate;  
forming a conductive shield on the semi-conductive or conductive surface; and  
removing a portion of the conductive shield, exposing a central region of the  
semi-conductive or conductive surface and leaving a remaining part of the conductive  
shield.

8. (original) A method according to claim 7 further comprising the step of anodizing the central region of the semi-conductive or conductive surface to create an anodized region in the semi-conductive or conductive surface.
9. (original) A method according to claim 8, further comprising:
  - removing the remaining part of the conductive shield;
  - forming a dielectric layer on the semi-conductive or conductive surface; and
  - removing a portion of the dielectric layer above the anodized region.
10. (original) A method according to claim 9, further comprising:
  - forming a conductive layer on the remaining portion of the first dielectric layer and on the anodized region;
  - forming a second dielectric layer on the conductive layer;
  - forming a second conductive layer on the second dielectric layer; and
  - removing a portion of the third conductive layer and the second dielectric layer above the anodized region.
11. (original) A method according to claim 1, further comprising the step of selecting silicon as the semi-conductive or conductive surface.
12. (original) A method according to claim 7, further comprising the step of selecting a metal as the conductive shield.
13. (original) A fabrication method for improving electron emission in a selected area of a semi-conductive or conductive flat emitter surface, comprising:
  - forming a semi-conductive or conductive flat emitter surface on a substrate in a manner ensuring that upon application of an electric field at the semi-conductive or conductive flat emitter surface an intensity of the electric field at a central area of the flat

emitter surface is at least as great as an intensity of the electric field at a perimeter of the flat emitter surface; and

anodizing the semi-conductive or conductive flat emitter surface by generating the electric field at the semi-conductive or conductive flat emitter surface to form pores in the semi-conductive or conductive flat emitter surface wherein the pores are proportionally concentrated according to the electric field intensity.

14. (original) A method for improving electron emission according to claim 13 wherein the forming step further comprises:

forming a dielectric layer on the substrate;

removing a portion of the dielectric layer, leaving a remaining part of the dielectric layer and exposing a central region of the substrate; and

forming the semi-conductive or conductive flat emitter surface on a portion of the remaining part of the dielectric layer and on the central region of the substrate.

15. (original) A method for improving electron emission according to claim 14 further comprising the step of anodizing the semi-conductive or conductive surface to form an anodized region of the semi-conductive or conductive surface above the central region of the substrate.

16. (original) A method for improving electron emission according to claim 15, further comprising:

forming a second dielectric layer on the semi-conductive or conductive flat emitter surface;

forming a conductive layer on the second dielectric layer;

forming a second conductive layer on the first conductive layer;

forming a third dielectric layer on the second conductive layer;

forming a third conductive layer on the third dielectric layer; and

removing a portion of the second conductive layer, the third dielectric layer and the third conductive layer above the anodized region.

17. (original) A method for improving electron emission according to claim 14, further comprising:

- forming a conductive layer on the semi-conductive or conductive flat emitter surface;
- forming a second dielectric layer on the conductive layer;
- forming a second conductive layer on the second dielectric layer; and
- removing a portion of the first conductive layer, the second dielectric layer and the second conductive layer above an area of contact between the semi-conductive or conductive flat emitter surface and the substrate, leaving a remaining part of the second conductive layer and uncovering a central region of the semi-conductive or conductive flat emitter surface.

18. (original) A method for improving electron emission according to claim 17, further comprising:

- anodizing the central region of the semi-conductive or conductive flat emitter surface to form an anodized region in the semi-conductive or conductive surface;
- forming a third dielectric layer on the anodized region; and
- forming a third conductive layer on the remaining part of the second conductive layer and on the third dielectric layer.

19. (original) A method for improving electron emission according to claim 13 wherein the forming step further comprises:

- forming the semi-conductive or conductive flat emitter surface on the substrate;
- forming a conductive shield on the semi-conductive or conductive flat emitter surface;
- removing a portion of the conductive shield to expose a central region of the semi-conductive or conductive flat emitter surface.

20. (original) A method for improving electron emission according to claim 19 further comprising the step of anodizing the central region of the semi-conductive or conductive flat emitter surface after removing a portion of the conductive shield.

21. (original) A method for improving electron emission according to claim 20, further comprising:

- removing the remaining portion of the conductive shield;
- forming a dielectric layer on the semi-conductive or conductive flat emitter surface; and
- removing a portion of the dielectric layer above the central region of the semi-conductive or conductive flat emitter surface.

22. (original) A method for improving electron emission according to claim 21, further comprising:

- forming a second dielectric layer on the anodized region;
- forming a conductive layer on the remaining portion of the first dielectric layer and on the second dielectric layer;
- forming a third dielectric layer on the conductive layer;
- forming a second conductive layer on the third dielectric layer; and
- removing a portion of the third conductive layer and the third dielectric layer above the anodized region.

23. (original) A method according to claim 13, further comprising the step of selecting silicon as the semi-conductive or conductive surface.

24. (original) A method according to claim 19, further comprising the step of selecting a metal as the conductive shield.

25. (original) A method for fabricating a porous electron emission device to improve electron emission characteristics of the porous electron emission device, the method comprising:

- forming a dielectric barrier over a substrate;
- opening at least one selected region of the dielectric barrier to expose a central region of the underlying substrate where flat emitters are to be located;
- forming a semi-conductive or conductive surface over the dielectric barrier and the central region of the underlying substrate; and
- anodizing the semi-conductive or conductive surface wherein a central area of the semi-conductive or conductive surface has improved electron emission efficiency over an outer perimeter thereof.

26. (original) A method for fabricating porous semi-conductive or conductive flat emitters utilized as field emission emitters to improve their electron emission characteristics, the method comprising:

- forming a semi-conductive or conductive surface over a substrate;
- forming a metal shield over the semi-conductive or conductive surface;
- opening a selected region of the metal shield to expose a central region of the semi-conductive or conductive surface where the flat emitter is to be located; and
- anodizing the semi-conductive or conductive surface to form a porous region in the central region of the semi-conductive or conductive surface wherein the metal shield causes an electric field intensity in the semi-conductive or conductive surface to be substantially uniform so that an intensity of the electric field at a central area of the surface is at least as great as an intensity of the electric field at a perimeter of surface.

27-29. (Withdrawn)